TOSHIBA CMOS DIGITAL INTEGRATED CIRCUIT SILICON MONOLITHIC

T6C13B

COLUMN AND ROW DRIVER FOR A DOT MATRIX LCD

The T6C13B is a 240-channel-output column and row driver for an STN dot matrix LCD.
The T6C13B features a 42-V LCD drive voltage and a 20-MHz maximum operating frequency. The T6C13B is able to drive LCD panels with a duty ratio of up to 1/480.

Unit: mm

T6C13B	LEAD PITCH	
	IN	OUT
(UAN, 5DS)	0.50	0.086

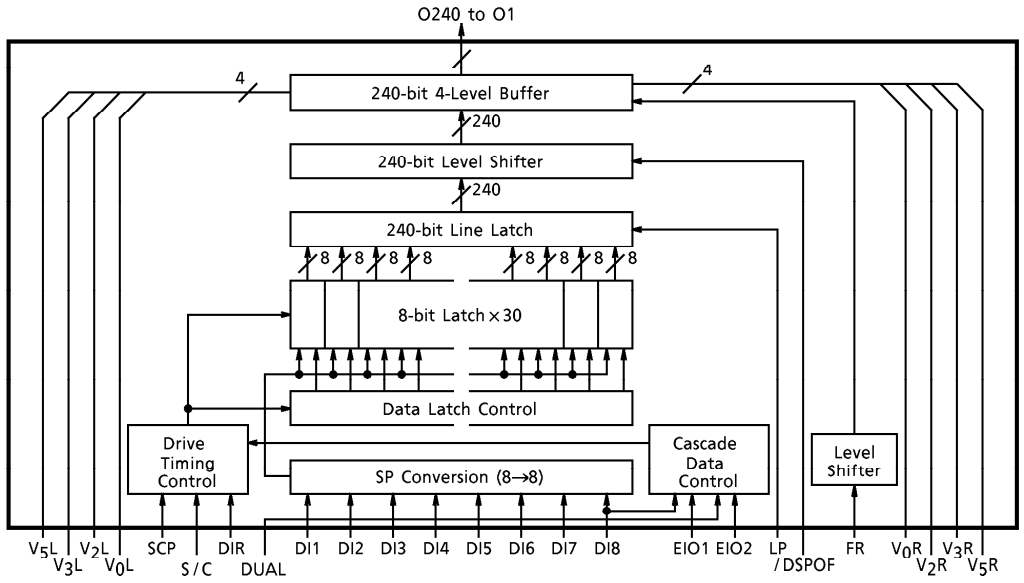
Please contact Toshiba or an authorized Toshiba dealer for information on package dimensions.

TCP (Tape Carrier Package)

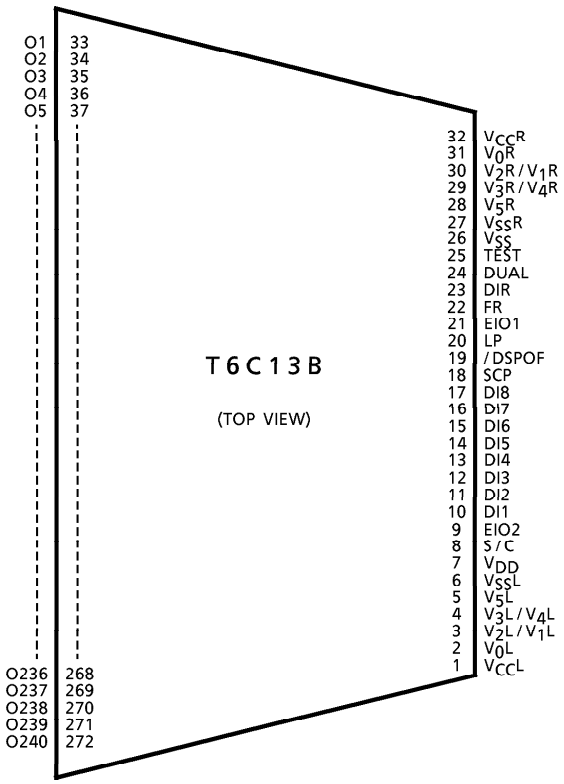
FEATURES

- Display duty application : to 1/480
- LCD drive signal : 240
- Data transfer : 8-bit bidirectional
- Operating frequency : 27MHz (V_{DD} = 4.5 to 5.5V)
- LCD drive voltage : 14 to 40V
- Power supply voltage : 2.7 to 5.5V
- Operating temperature : −20 to 75°C
- LCD drive output resistance : 800Ω (max) (20V, 1/13 bias)
- Display-off function : When /DSPOF is L, all LCD drive outputs (O1 to O240) remain at the V_5 level.
- Low power consumption : Cascade connection and auto enable transfer functions are available.

BLOCK DIAGRAM



PIN ASSIGNMENT



(*) The above diagram shows the pin configuration of the LSI Chip, not that of the tape carrier package.

PIN FUNCTIONS

PIN NAME	I/O	FUNCTIONS	LEVEL
O1 to O240	Output	Output for LCD drive signal	V_0 to V_5
EIO1, EIO2	I/O	Input/output for enable signal DIR selects In or Out. Connect EIO (IN) of 1st LSI to L. For a cascade connection, connect EIO (OUT) to EIO (IN) of next LSI.	V_{DD} to V_{SS}
DI1 to DI8	Input	(Column mode) Input for data signal	
		(Row mode) DI1 to DI7 : Fix to H or L DI8 : 121st enable terminal in dual mode.	
DIR	Input	(Direction) Input for data flow direction select	
/DSPOF	Input	(Display off) /DSPOF = L : Display-off mode, (O1 to O240) remain at the V_5 level. /DSPOF = H : Display-on mode, (O1 to O240) are operational.	
DUAL	Input	(Column mode) Fix to H or L	
		(Row mode) Terminal for dual input mode or single input mode select	
LP	—	(Column mode) Display data is latched falling edges of LP. When EIO (IN) = L, setting $\overline{SCP}$·LP = H enables the 1st LSI.	
		(Row mode) Input for shift clock pulse	
FR	Input	(Frame) Input for frame signal	
SCP	Input	(Column mode) Input for shift clock pulse	
		(Row mode) Fix to H or L	
TEST	Input	(Test) Fix to L	
S/C	Input	Input for mode select : H = Column mode, L = Row mode	
V_{DD}	—	Power supply for internal logic (+5.0V)	—
V_{SS}	—	Power supply for internal logic (0V)	
V_{SS}L·R	—	Power supply for LCD drive circuit	
V_5L·R	—	Power supply for LCD drive circuit	
$V_{3/4}$L·R	—	Power supply for LCD drive circuit	
$V_{2/1}$L·R	—	Power supply for LCD drive circuit	
V_0L·R	—	Power supply for LCD drive circuit	
V_{CC}L·R	—	Power supply for LCD drive circuit	

RELATION BETWEEN FR, DATA INPUT AND OUTPUT LEVEL

FR	DATA INPUT (DI1 to DI8)	/DSPOF	OUTPUT LEVEL (COLUMN MODE)	OUTPUT LEVEL (ROW MODE)
L	L	H	V_3	V_4
L	H	H	V_5	V_0
H	L	H	V_2	V_1
H	H	H	V_0	V_5
—	—	L	V_5	V_5

DATA INPUT FORMAT

Column mode

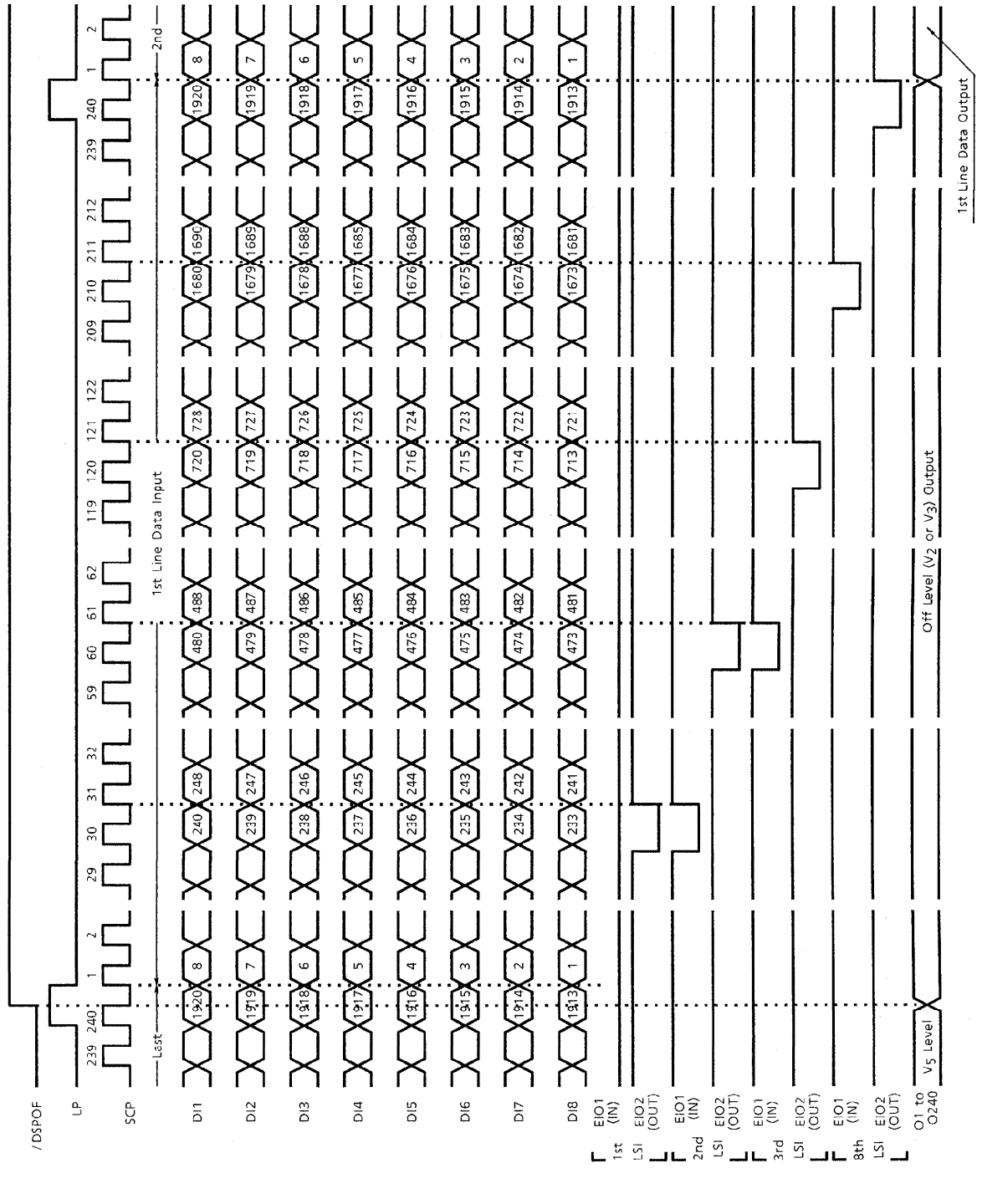
DIR	BIT MODE	ENABLE PIN		(*1)	INPUT DATA LINE AND OUTPUT BUFFERS							
		(EIO1)	(EIO2)		DI1	DI2	DI3	DI4	DI5	DI6	DI7	DI8
H	8-BIT	IN	OUT	L	O240	O239	O238	O237	O236	O235	O234	O233
				F	O8	O7	O6	O5	O4	O3	O2	O1
L		OUT	IN	L	O1	O2	O3	O4	O5	O6	O7	O8
				F	O233	O234	O235	O236	O237	O238	O239	O240

(*1) L : Last data F : First data

Row mode

DUAL	DIR	DATA FLOW	DATA INPUT TERMINALS		
			EIO1	EIO2	DI8
L	L	O240→O1	OUT	IN	—
L	H	O1→O240	IN	OUT	—
H	L	O120→O1 O240→O121	OUT	IN	IN
H	H	O1→O120 O121→O240	IN	OUT	IN

TIMING DIAGRAM (Column mode)



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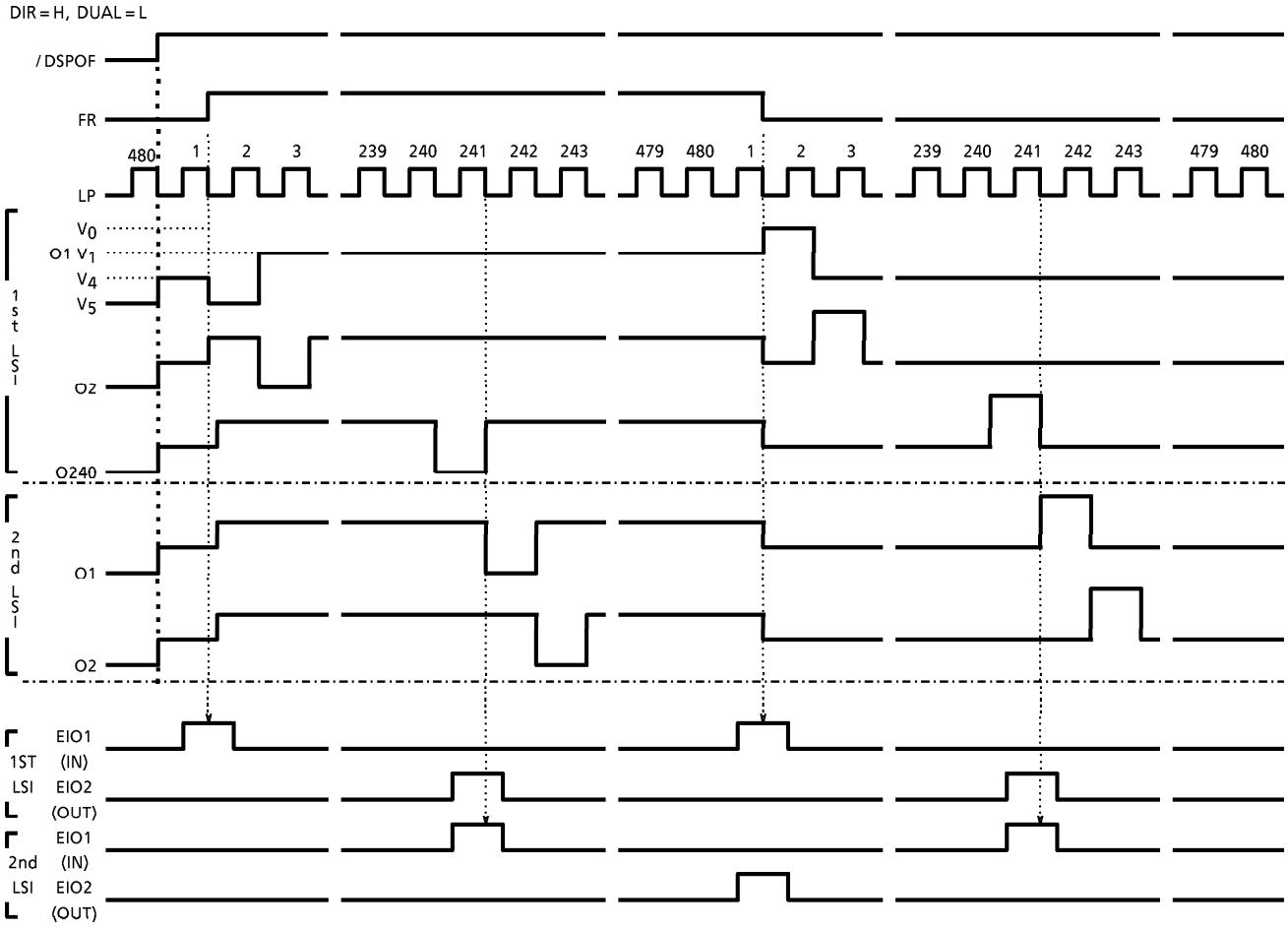
TIMING DIAGRAM (Row mode)



ABSOLUTE MAXIMUM RATINGS

(Ensure that the following conditions are maintained : $V_{CC} \geqq V_0 \geqq V_{2,\ 1} \geqq V_{3,\ 4} \geqq V_5 \geqq V_{SS}$)

ITEM	SYMBOL	PIN NAME	RATING	UNIT
Supply Voltage 1	V_{DD}	V_{DD}	−0.3 to 6.5	V
Supply Voltage 2	V_{CC}	V_{CC}L/R	−0.3 to 42.0	V
Supply Voltage 3	V_0, V_2	V_0L/R, $V_{2,\ 1}$L/R	−0.3 to V_{CC}+0.3	V
Supply Voltage 4	V_3, V_5	$V_{3,\ 4}$L/R, V_5L/R	−0.3 to 42.0	V
Input Voltage	V_{IN}	(*2)	−0.3 to V_{DD}+0.3	V
Operating Temperature	T_{opr}	—	−20 to 75	°C
Storage Temperature	T_{stg}	—	−40 to 125	°C

(*2) SCP, FR, LP, DIR, DUAL, EIO1, EIO2, DI1 to DI8, /DSPOF, TEST, S/C

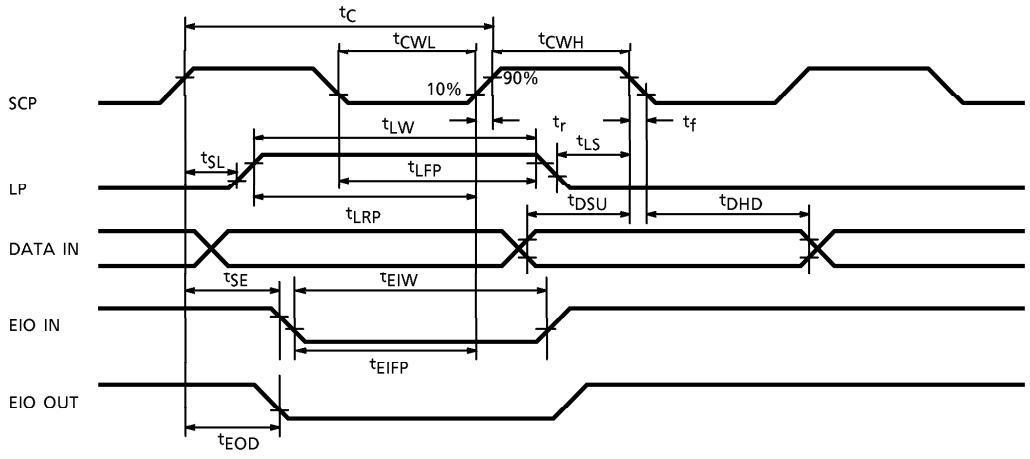
ELECTRICAL CHARACTERISTICS

DC CHARACTERISTICS (Unless otherwise noted, V_{SS} = 0V, V_{DD} = 2.7 to 5.5V, Ta = −20 to 75°C)

ITEM		SYMBOL	TEST CIR-CUIT	TEST CONDITION	MIN	TYP.	MAX	UNIT	PIN NAME
Supply Voltage 1		V_{DD}	—	—	2.7	5.0	5.5	V	V_{DD}
Supply Voltage 2		V_{CC}	—	—	14.0	—	40.0		V_{CC}L/R
Input Voltage	H Level	V_{IH}	—	—	0.8 V_{DD}	—	V_{DD}		SCP, FR, LP, DIR, DUAL, EIO1, EIO2, DI1 to DI8, /DSPOF, TEST, S/C
	L Level	V_{IL}	—	—	0	—	0.2 V_{DD}		
Output Voltage	H Level	V_{OH}	—	I_{OH} = −0.5mA	V_{DD} −0.5	—	V_{DD}		EIO1, EIO2
	L Level	V_{OL}	—	I_{OL} = 0.5mA	0	—	0.5		
Output Resistance	H Level	R_{OH}	—	$V_{OUT} = V_0 - 0.5V$ (*3)	—	0.4	0.8	kΩ	O1 to O240
	M Level	R_{OM}	—	$V_{OUT} = V_2 \pm 0.5V$ (*3)	—	0.4	0.8		
		R_{OM}	—	$V_{OUT} = V_3 \pm 0.5V$ (*3)	—	0.4	0.8		
	H Level	R_{OL}	—	$V_{OUT} = V_5 + 0.5V$ (*3)	—	0.4	0.8		
Current Consumption		I_{DD}	—	V_{DD} = 5.5V V_{CC} = 42V f_{FR} = 40Hz f_{scp} = 8.0MHz Input data: every bit inverted V_{IH} = 5.5V, V_{IL} = 0V (Current consumption while the internal data receiver is operating	—	—	81.5	mA	V_{DD}
		I_{DD} ST/BY	—	Current consumption while the internal data receiver is sleeping	—	—	240	μA	V_{DD}

(*3) V_{CC} = 20V, 1/13bias

AC ELECTRICAL CHARACTERISTICS (COLUMN MODE)



TEST CONDITIONS (1) (V_{SS} = 0V, V_{DD} = 2.7 to 4.5V, V_{CC} = 14 to 42V, Ta = – 20 to 75°C)

ITEM	SYMBOL	TEST CONDITION	MIN	MAX	UNIT
Clock Cycle	t_C	—	76	—	ns
SCP Pulse Width	t_{CWH}, t_{CWL}	—	26	—	
Data Set-up Time	t_{DSU}	—	26	—	
Data Hold Time	t_{DHD}	—	26	—	
SCP Rise / Fall Time	t_r, t_f	—	—	(*4)	
LP Rise Time	t_{LRP}	—	26	—	
LP Fall Time	t_{LFP}	—	26	—	
LP Pulse Width	t_{LW}	—	26	—	
SCP-to-LP Delay Time (SCP→LP)	t_{SL}	—	26	—	
LP-to-SCP Delay Time (LP→SCP)	t_{LS}	—	26	—	
EIO IN Rise Time	t_{EIFP}	—	26	—	
EIO IN Pulse Width	t_{EIW}	—	26	—	
SCP-to-EIO Delay Time (SCP→EIO)	t_{SE}	—	0	—	
EIO OUT Delay Time	t_{EOD}	(*5)	—	50	

(*4) t_r, $t_f \leqq (t_C - t_{CWH} - t_{CWL}) / 2$ and t_r, $t_f \leqq 50$ns

(*5) C_L = 10pF

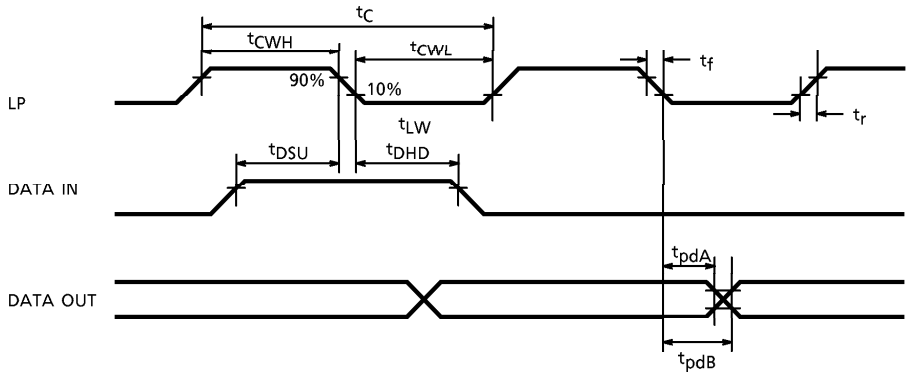
TEST CONDITIONS (2) (V_{SS} = 0V, V_{DD} = 4.5 to 5.5V, V_{CC} = 14 to 42V, Ta = – 20 to 75°C)

ITEM	SYMBOL	TEST CONDITION	MIN	MAX	UNIT
Clock Cycle	t_C	—	37	—	ns
SCP Pulse Width	t_{CWH}, t_{CWL}	—	15	—	
Data Set-up Time	t_{DSU}	—	15	—	
Data Hold Time	t_{DHD}	—	15	—	
SCP Rise / Fall Time	t_r, t_f	—	—	(*6)	
LP Rise Time	t_{LRP}	—	15	—	
LP Fall Time	t_{LFP}	—	15	—	
LP Pulse Width	t_{LW}	—	15	—	
SCP-to-LP Delay Time	t_{SL}	—	15	—	
LP-to-SCP Delay Time	t_{LS}	—	15	—	
EIO IN Fall Time	t_{EIFP}	—	15	—	
EIO IN Pulse Width	t_{EIW}	—	15	—	
SCP-to-EIO Delay Time	t_{SE}	—	0	—	
EIO OUT Delay Time	t_{EOD}	(*7)	—	25	

(*6) t_r, $t_f \leqq (t_C - t_{CWH} - t_{CWL}) / 2$ and t_r, $t_f \leqq 50$ns

(*7) C_L = 10pF

AC ELECTRICAL CHARACTERISTICS (Row mode)



TEST CONDITIONS (1) (V_{SS} = 0V, V_{DD} = 2.7 to 4.5V, V_{CC} = 14 to 42V, Ta = – 20 to 75°C)

ITEM	SYMBOL	TEST CONDITION	MIN	MAX	UNIT
Clock Cycle	t_C	LP	250	—	ns
LP Pulse Width H	t_{CWH}	LP	40	—	
LP Pulse Width L	t_{CWL}	LP	170	—	
SCP Rise / Fall Time	t_r, t_f	LP, FR, EIO1, EIO2, DI8	—	(*8)	
Data Set-up Time	t_{DSU}	EIO1, EIO2, DI8	100	—	
Data Hold Time	t_{DHD}	EIO1, EIO2, DI8	0	—	
EIO OUT Delay Time A (*9)	t_{pdA}	EIO1, EIO2	40	—	
EIO OUT Delay Time B (*9)	t_{pdB}	EIO1, EIO2	0	130	

TEST CONDITIONS (2) (V_{SS} = 0V, V_{DD} = 4.5 to 5.5V, V_{CC} = 14 to 42V, Ta = – 20 to 75°C)

ITEM	SYMBOL	TEST CONDITION	MIN	MAX	UNIT
Clock Cycle	t_C	LP	150	—	ns
LP Pulse Width H	t_{CWH}	LP	20	—	
LP Pulse Width L	t_{CWL}	LP	100	—	
SCP Rise / Fall Time	t_r, t_f	LP, FR, EIO1, EIO2, DI8	—	(*10)	
Data Set-up Time	t_{DSU}	EIO1, EIO2, DI8	50	—	
Data Hold Time	t_{DHD}	EIO1, EIO2, DI8	0	—	
EIO OUT Delay Time A (*11)	t_{pdA}	EIO1, EIO2	20	—	
EIO OUT Delay Time B (*11)	t_{pdB}	EIO1, EIO2	0	100	

(*8, 10) t_r, $t_f \leqq (t_C - t_{CWH} - t_{CWL}) / 2$ and t_r, $t_f \leqq 50$ns

(*9, 11) C_L = 10pF

NOTE

Insert the bypass capacitor (0.1μF) between V_{DD} and V_{SS} and between V_{CC} and V_{SS} to decrease power supply noise.

Place the bypass capacitor as close to the LSI as possible.